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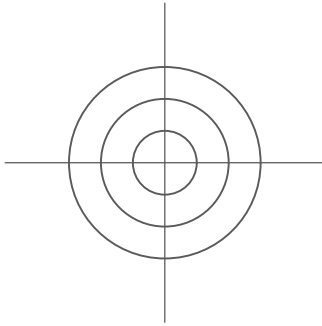
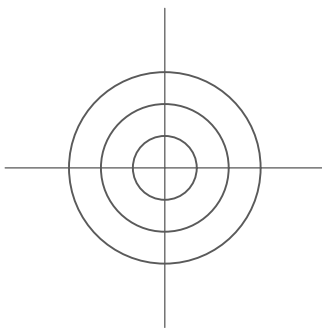
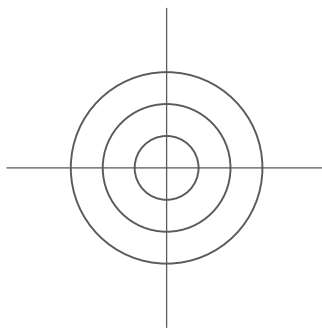
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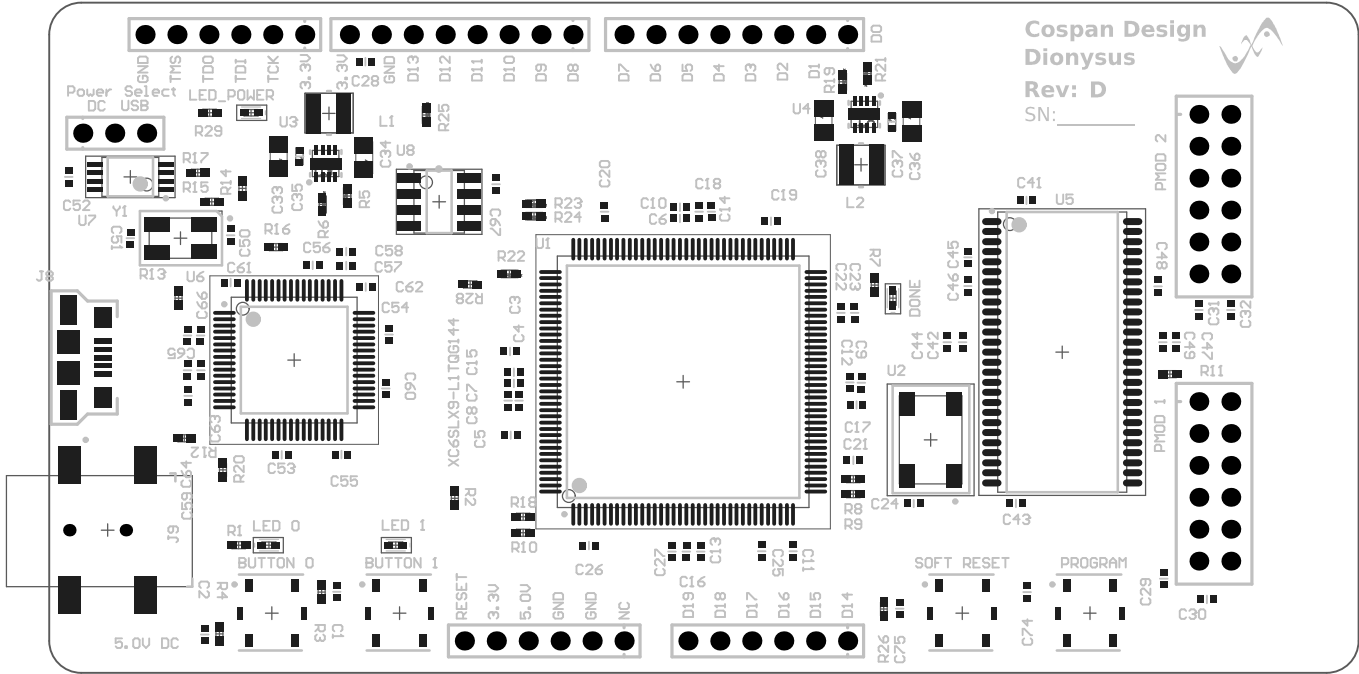
5

6



Layer Stack Up Detail for: Dionysus.PcbDoc

Layer Name
Component Side: 1.0 Oz
Ground Plane: 1.0 Oz
Power Plane: 1.0 Oz
Solder Side: 1.0 Oz



Fabrication Notes

- Overall board height: 62mils
- 20mil pullback on inner planes
- 1.0 Oz copper on top and bottom
- 1.0 Oz copper on internal signal, power and ground layers

Design Notes

- Unless otherwise stated all dimensions are in mils

LAYER - GERBER LAYERS - DESCRIPTION

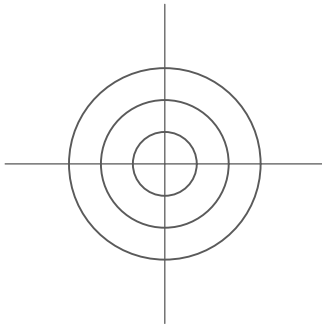
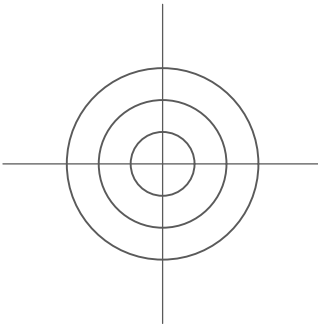
GTO - TOP SILKSCREEN

- MECHANICAL LAYERS
- 01 Component Outline
 - 02 PCB Boundary
 - 03 Pinout ID
 - 04
 - 05
 - 06 Fabrication Notes
 - 07 Component Designators
 - 08
 - 09
 - 10
 - 11 Design Information
 - 12 Dimension
 - 13 Height Information
 - 14
 - 15 Assembly
 - 16 Sheet

Multi-Layer

B
Size

Dave McCoy	Cospan Design			
Dave McCoy				
9/11/2012	D	9/11/2012	D	
1:1	Dionysus.PcbDoc		Sheet 1	of 1



Layer Stack Up Detail for: Dionysus.PcbDoc

Layer Name
Component Side: 1.0 Oz
Ground Plane: 1.0 Oz
Power Plane: 1.0 Oz
Solder Side: 1.0 Oz

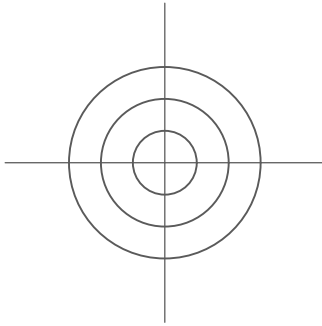


Fabrication Notes

- Overall board height: 62mils
- 20mil pullback on inner planes
- 1.0 Oz copper on top and bottom
- 1.0 Oz copper on internal signal, power and ground layers

Design Notes

- Unless otherwise stated all dimensions are in mils



LAYER - GERBER LAYERS - DESCRIPTION

GB0 - BOTTOM SILKSCREEN

- MECHANICAL LAYERS
- 01 Component Outline
 - 02 PCB Boundary
 - 03 Pinout ID
 - 04
 - 05
 - 06 Fabrication Notes
 - 07 Component Designators
 - 08
 - 09
 - 10
 - 11 Design Information
 - 12 Dimension
 - 13 Height Information
 - 14
 - 15 Assembly
 - 16 Sheet

Multi-Layer

B
Size

Dave McCoy	Cospan Design		
Dave McCoy			
9/11/2012	D	9/11/2012	D
1:1	Dionysus.PcbDoc		
	Sheet 1 of 1		